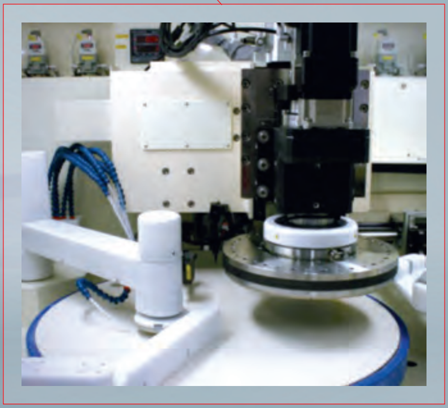
GnP POLI - 762



Intelligent CMP System For Research & Development G&P Technology

SPECIFICATIONS

· Head, Table	30 ~ 200 rpm, Rotational motion, Head oscillation (± 12㎜)
· Size	1,580W 1,480D 1,960H㎜
· Platen size	Ø762㎜,(30inch), Teflon coated Aluminum
· Pressing method	Variable air pressure electronic controller · Membrane Type : 70 ~ 350 g/㎠ (1psi ~ 5psi) · Wafer Down Force & Conditioning Load Monitoring System
· Process	Automatic sequence, Dry - in / Wet - out

OPTIONS

- Pad Profile Measurement
- Friction Force & Temperature Monitoring System

APPLICATIONS

· Workpiece	Max 12 inch wafer
· CMP Process	Si CMP, Oxide CMP (BPSG, TEOS, ThOx), Metal CMP (W, Cu), STI, etc.

CHARACTERISTICS

- 300㎜ CMP Machine for R & D
- Stable repeatability (WTWNU < 5%)
- High rigidity
- Wide application for CMP R & D